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Description

Method for heat dissipation in mobile radio devices,  
and a corresponding mobile radio device

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The present invention relates to a method for heat  
dissipation in mobile radio devices, and to a  
corresponding mobile radio device. An operating range  
with an environmental temperature generally of +55°C is  
10 specified in mobile telecommunications terminals and in  
mobile radio devices, such as mobile telephones, PDAs  
and laptops. These mobile radio devices are constructed  
like a shell for the electronic components and the  
temperature rises from shell to shell towards the  
15 components. The maximum temperature is functionally  
limited. The temperature close to the individual  
components in this case may be an environmental  
temperature of 82°C, while the temperature of the  
component itself may be up to 100°C. The electronic  
20 components convert the majority of the energy/power  
supplied to them to heat, which heats not only the  
component itself but also its immediate surrounding  
area. The power that is converted to heat is  
accordingly a power loss.

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In new, future mobile radio devices with the  
introduction of data services by means of GPRS with a  
so-called Class 10, the power with two transmission  
time slots is doubled, which also means that the power  
30 loss produced by the electronic components is also  
virtually doubled. The subdivision into "classes"  
relates to details of the configuration of the  
transmission and reception time slots. In Class 10, two  
transmission time slots are possible, which means that  
35 not only the transmission power but also the power loss  
is doubled.

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In even higher GPRS classes, such as GPRS Class 12, the power loss is up to a multiple of this. This results in a threat of the components being overheated after a certain operating time.

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The following table provides a rough overview of the GPRS classes:

Multislot Class	Transmission slots	Reception slots	Number of slots (usable)
1	1	1	2
...			
8	1	4	5
...			
10	2	4	5
...			
12	4	4	5

10 This type of problem has not occurred in the past in the field of mobile telecommunications since this technology is only now being introduced. In the past, mobile radio devices have been implemented and operated on the basis of GPRS Class 8.

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In other electronic devices, such as desktop computers, heat sinks or fans have been mounted on the temperature-critical components. When fitting heat sinks, care must be taken to ensure that good thermal  
20 coupling is provided between the heat sink and the electrical component which is heated by the power loss. In order to exclude air, as a poor thermal conductor, spaces between the corresponding component and the heat sink are filled with thermally conductive sheets or  
25 thermally conductive pastes.

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Furthermore the distribution of the heat in electrical components can be influenced by a matched structure.

5 Thermally conductive sheets and thermally conductive pastes are admittedly better thermal conductors than air, but are also not adequate to ensure satisfactory heat dissipation for electrical components.

10 One object of the present invention was thus to provide a method which makes it possible to ensure good and satisfactory heat dissipation from electronic components in mobile radio devices. A further object of the present invention was to provide a corresponding mobile radio device.

15 This object is achieved by a method according to the invention as claimed in claim 1, and by a mobile radio device according to the invention as claimed in claim 5. Further advantageous embodiments of the  
20 invention are specified in the corresponding dependent claims.

Claim 1 provides a method for heat dissipation in mobile radio devices having heat-emitting, electrical  
25 components, in which the heat-emitting components are brought into heat-dissipating contact with a metal foil.

30 In one preferred embodiment of the method according to the invention, the metal foil is corrugated and/or is structured in the form of a honeycomb. The use of a metal foil which is corrugated and/or is structured in the form of a honeycomb minimizes the resistance for heat dissipation. The capability of the metal foil that  
35 is corrugated and/or is structured in the form of a honeycomb to deform means that

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any intermediate spaces which occur are completely filled, thus ensuring optimum heat dissipation. The metal foil which is corrugated and/or in the form of a honeycomb can be arranged in an interlocking manner on the surfaces which can be brought into contact for heat dissipation.

In a further preferred embodiment of the method according to the invention, the metal foil is brought into contact with a heat sink. The heat sink may, for example, be a metallic body which either has a large area for radiated emission and/or a large volume as a heat sink.

In another preferred embodiment, the metal foil is itself used as a heat sink. The magnitude of the heat loss to be dissipated, in particular, determines whether the metal foil is itself adequate as a heat sink. The honeycomb and/or corrugated structure provided according to the invention offers a very large heat-emitting surface area.

Furthermore, the invention covers a mobile radio device having heat-emitting electrical components, in which the components are each in heat-dissipating contact with a metal foil.

The metal foil is preferably corrugated and/or has a honeycomb structure. The use of a metal foil which is corrugated or is structured in the form of a honeycomb enlarges the radiation-emitting surface area. The heat dissipation resistance is minimized on the one hand by the use of a metallic foil as well as by its structure, which is corrugated or is in the form of a honeycomb.

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Furthermore, in a further preferred embodiment of the mobile radio device according to the invention, the metal foil is in heat-dissipating contact with a heat sink.

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In another preferred embodiment of the mobile radio device according to the invention, the metal foil itself acts as a heat sink. Its honeycomb and/or corrugated structure means that it has a very large heat-emitting surface area.

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Furthermore, the present invention covers the use of a metal foil which is corrugated and/or is structured in the form of a honeycomb for heat dissipation from heat-emitting electrical components in mobile radio devices.

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Further advantages will be explained in more detail with reference to the following figures, in which:

Figure 1 shows a schematic illustration of one implemented embodiment of the method according to the invention;

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Figure 2 shows a schematic illustration of another implemented embodiment of the method according to the invention;

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Figure 3 shows a schematic illustration of a further implemented embodiment of the method according to the invention.

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Figure 1 shows a printed circuit board 1 which is fitted on one side with components 2 which develop a large amount of heat. A heat sink 4 in the form of a cold plate is arranged on the other side of the printed circuit board 1 by means of suitable connecting elements 3 which, for example, may be screws or rivets.

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During the fitting of the heat sink 4, good thermal coupling between the heat sink

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and the electrical components 2 is the critical factor ensuring that the components 2 are not excessively heated, which could thus possibly lead to destruction of the components 2. In order to avoid poor thermal  
5 conduction, a metal foil 5 or a metal paste is, according to the invention, inserted in the space which occurs between the printed circuit board 1 and the heat sink 4.

10 Figure 2 shows another possible way to carry out the method according to the invention. The figure once again shows a printed circuit board 1 which is fitted with a component 2 that produces heat losses, on one side. A shielding cover 6 is also provided above the  
15 component 2, for shielding. A heat sink 4 is arranged on the other side of the printed circuit board 1. This may be a heat sink, a battery or a chassis. According to the invention, a metal foil 5, which is corrugated and/or structured in the form of a honeycomb, is  
20 arranged in the resultant spaces between the component 2 or the printed circuit board 1 and the shielding cover 6 or the heat sink 4. The capability of the metal foil 5, which is corrugated and/or structured in the form of a honeycomb, to deform allows very good contact  
25 for heat transfer. On the one hand, the metal foil 5 may provide only the junction to a heat sink 4, as in this case in the space between the heat sink 4 and the printed circuit board 1. Furthermore, the metal foil 5 could itself act as a heat sink. This is because the  
30 use of a metal foil 5 with a corrugated or honeycomb structure considerably enlarges the radiation-emitting surface area.

Figure 3 shows a further possible way to implement the  
35 method according to the invention. In this case as well, the figure shows a printed circuit board 1 with a lossy component 2 arranged on one side of the printed

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circuit board 1. Furthermore,



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a plastic part 7 is arranged on the other side of the printed circuit board 1. A metal foil 5 which is in the form of a honeycomb and/or is corrugated is provided between the plastic part 7 and the printed circuit board 1 and can be matched to the respective surfaces by virtue of its capability to be deformed well. By virtue of its structure, the metal foil 5 itself has a very large heat-emitting surface area, which represents an additional factor.